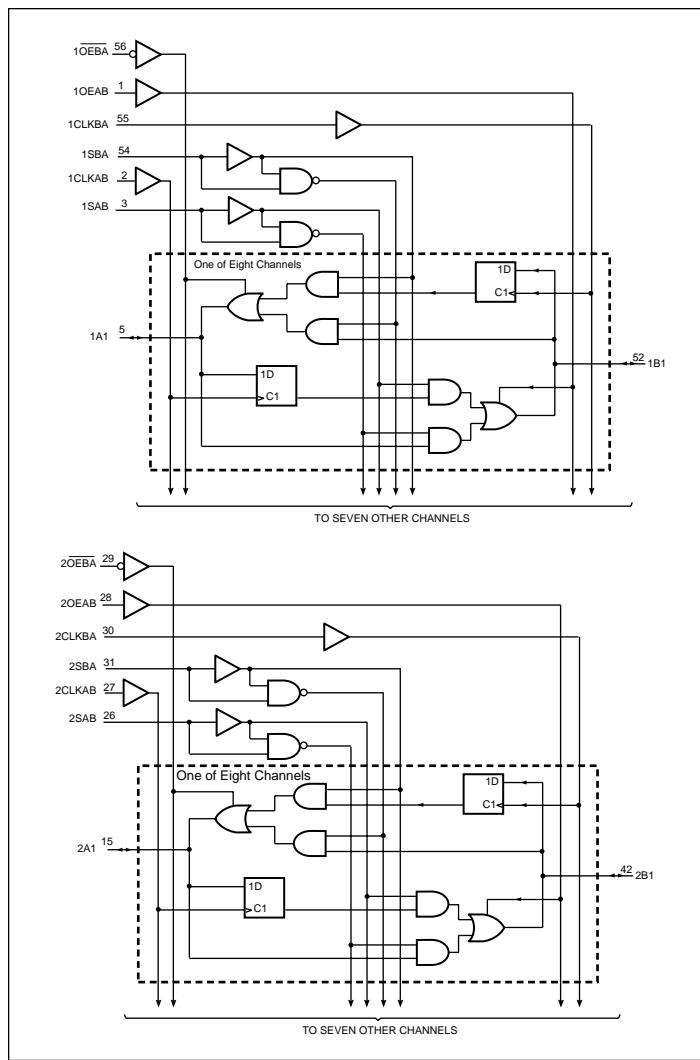


## 2.5V 16-Bit Bus Transceiver and Register with 3-State Outputs

### Product Features

- PI74ALVTC16652 is designed for low voltage operation,  $V_{DD} = 1.65V$  to  $3.6V$
- Supports Live Insertion
- 3.6V I/O Tolerant Inputs and Outputs
- Bus Hold
- High Drive,  $-32/64mA @ 3.3V$
- Uses patented noise reduction circuitry
- Power-off high impedance inputs and outputs
- Industrial operation at  $-40^{\circ}C$  to  $+85^{\circ}C$
- Packages available:
  - 56-pin 240-mil wide plastic TSSOP (A56)
  - 56-pin 173-mil wide plastic TSVSOP (K56)

### Logic Block Diagram



### Product Description

Pericom Semiconductor's PI74ALVTC series of logic circuits are produced using the Company's advanced 0.35 micron CMOS technology, achieving industry leading speed.

The PI74ALVTC16652 is a 16-bit bus transceiver and register designed for low 1.65V to 3.6V V<sub>CC</sub> operation. It consists of D-type flip-flops and control circuitry arranged for multiplexed transmission of data directly from the data bus or from the internal storage registers. The device can be used as two 8-bit transceivers or one 16-bit transceiver. Complementary Output Enable (OEAB and OEBA) inputs are provided to control the transceiver functions. Select Control (SAB and SBA) inputs are provided to select whether real-time or stored data is transferred. A low input level selects real-time data, and a high input level selects stored data. Circuitry used for Select Control eliminates the typical decoding glitch that occurs in a multiplexer during the transition between stored and real-time data.

Data on the A or B bus, or both, can be stored in the internal D flip-flops by low-to-high transitions at the appropriate clock (CLKAB or CLKBA) inputs regardless of the levels on the Select Control or Output Enable inputs. When SAB and SBA are in the real-time transfer mode, it also is possible to store data without using the internal D-type flip-flops by simultaneously enabling OEAB and OEBA. In this configuration, each output reinforces its input. Thus, when all other data sources to the two sets of bus lines are in the high-impedance state, each set of bus lines remains at its last level configuration.

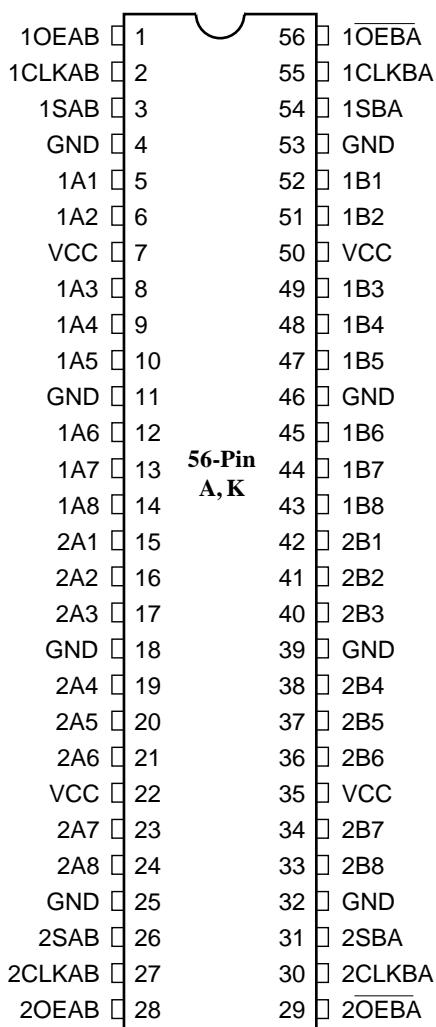
To ensure the high-impedance state during power up or power down, OEBA should be tied to V<sub>CC</sub> through a pull-up resistor and OEAB should be tied to GND through a pull-down resistor; the minimum value of the resistor is determined by the current-sinking current sourcing capability of the driver.

The family offers both I/O Tolerant, which allows it to operate in mixed 1.65/3.6V systems, and "Bus Hold," which retains the data input's last state preventing "floating" inputs and eliminating the need for pullup/down resistors.

### Product Pin Description

Pin Name	Description
OEAB	Output Enable Inputs (Active HIGH)
OEBA	Output Enable Inputs (Active LOW)
xCLKAB, xCLKBA	Clock Pulse Inputs
xSAB, xSBA	Select Control Inputs
xAx	Data Register A Inputs, Data Register B Outputs
xBx	Data Register B Inputs, Data Register A Outputs
GND	Ground
Vcc	Power

### Pin Configuration



### Truth Table<sup>(1)</sup>

Inputs						Data I/O*		Operation or Function
OEAB	OEBA	CLKAB	CLKBA	SAB	SBA	A1 - A8	B1 - B8	
L	H	H or L	H or L	X	X	Input	Input	Isolation
L	H	↑	↑	X	X	Input	Input	Store A and B data
X	H	↑	H or L	X	X	Input	Unspecified**	Store A, hold B
H	H	↑	↑	X**	X	Input	Output	Store A in both registers
L	X	H or L	↑	X	X	Unspecified**	Input	Hold A, store B
L	L	↑	↑	X	X**	Output	Input	Store B in both registers
L	L	X	X	X	L	Output	Input	Real-time B data to A bus
L	L	X	H or L	X	H	Output	Input	Stored B data to A bus
H	H	X	X	L	X	Input	Output	Real-time A data to B bus
H	H	H or L	X	H	X	Input	Output	Stored A data to B bus
H	L	H or L	H or L	H	H	Output	Output	Stored A data to B bus and stored B data to A bus

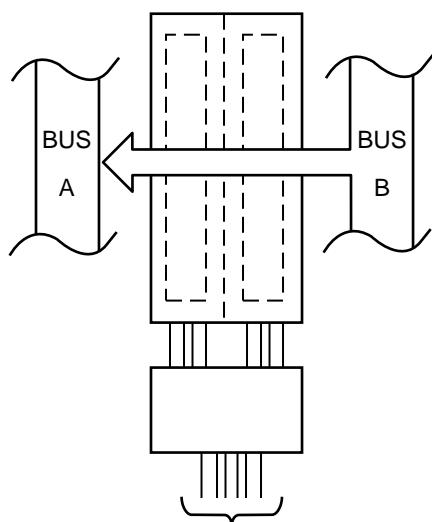
\* The data output functions may be enabled or disabled by a variety of level combinations at the OEAB or OEBA inputs. Data input functions are always enabled, i.e., data at the bus pins will be stored on every LOW-to-HIGH transition on the clock inputs.

\*\* Select control = L; clocks can occur simultaneously. Select control = H; to load both registers, clocks must be staggered.

#### Note:

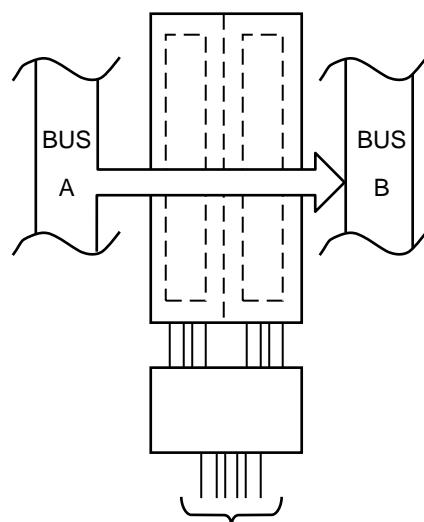
1. H = High Voltage Level, X = Don't Care,  
L = Low Voltage Level, ↑ = LOW-to-HIGH Transition

**REAL-TIME TRANSFER**  
**BUS B to A**



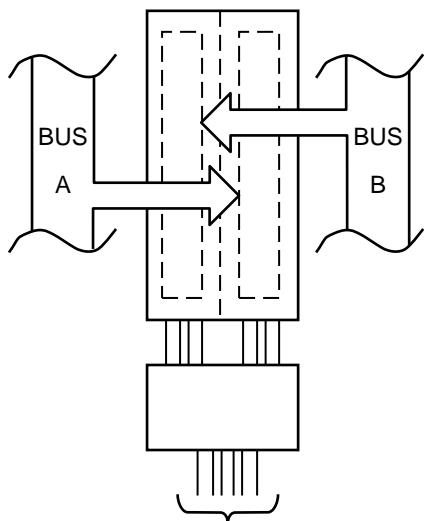
OEAB	<u>OEBA</u>	xCLKAB	xCLKBA	xSAB	xSBA
L	L	X	X	X	L

**REAL-TIME TRANSFER**  
**BUS A to B**



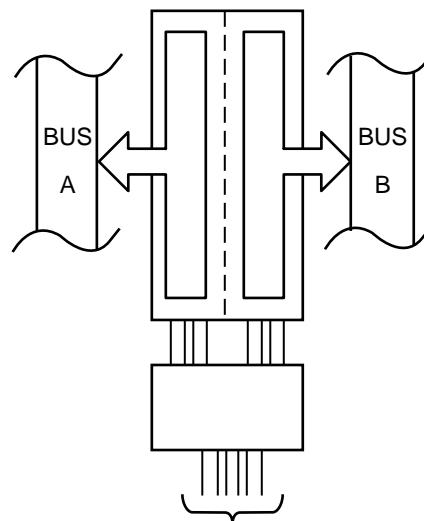
OEAB	<u>OEBA</u>	xCLKAB	xCLKBA	xSAB	xSBA
H	H	X	X	L	X

**STORAGE FROM**  
**A,B, or A and B**



OEAB	<u>OEBA</u>	xCLKAB	xCLKBA	xSAB	xSBA
X	H	↑	X	X	X
L	X	X	↑	X	X
L	H	↑	↑	X	X

**TRANSFER STORED**  
**DATA to A and/or B**



OEAB	<u>OEBA</u>	xCLKAB	xCLKBA	xSAB	xSBA
H	L	HorL	HorL	H	H

**Note:**

1. Cannot transfer data to A bus and B bus simultaneously.

## Maximum Ratings

(Above which the useful life may be impaired. For user guidelines, not tested.)

Supply Voltage Range, V <sub>DD</sub>	–0.5V to 4.6V
Input Voltage Range, V <sub>I</sub>	–0.5V to 4.6V
Output Voltage Range, V <sub>O</sub> (3-Stated)	–0.5V to 4.6V
Output Voltage Range, V <sub>O</sub> <sup>(1)</sup> (Active)	–0.5V to V <sub>DD</sub> + 0.5V
DC Input Diode Current (I <sub>IK</sub> ) V <sub>I</sub> < 0V	–50mA
DC Output Diode Current (I <sub>OK</sub> )	
V <sub>O</sub> < 0V	–50mA
V <sub>O</sub> > V <sub>DD</sub>	±50mA
DC Output Source/Sink Current (I <sub>OH</sub> /I <sub>OL</sub> )	–64/128mA
DC V <sub>DD</sub> or GND Current per Supply Pin (I <sub>CC</sub> or GND)	±100mA
Storage Temperature Range, T <sub>stg</sub>	–65°C to 150°C

### Note:

Stresses greater than those listed under MAXIMUM RATINGS may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect reliability.

## Recommended Operating Conditions<sup>(2)</sup>

			Min.	Max.	Units
V <sub>DD</sub>	Supply voltage	Operating	1.65	3.6	V
		Data Retention Only	1.2	3.6	
V <sub>IH</sub>	High-level input voltage	V <sub>DD</sub> = 2.7V to 3.6V	2.0		
V <sub>IL</sub>	Low-level input voltage	V <sub>DD</sub> = 2.7V to 3.6V		0.8	
V <sub>I</sub>	Input voltage		–0.3	3.6	
V <sub>O</sub>	Output voltage	Active State	0	V <sub>DD</sub>	mA
		Off State	0	3.6	
	Output current in I <sub>OH</sub> /I <sub>OL</sub>	V <sub>DD</sub> = 3.0V to 3.6V V <sub>DD</sub> = 3.0V to 3.6V V <sub>DD</sub> = 2.3V to 2.7V V <sub>DD</sub> = 1.65V to 1.95V		–32/64 ±24 ±18 ±6	
Δt/Δv	Input transition rise or fall rate <sup>(3)</sup>		0	10	ns/V
T <sub>A</sub>	Operating free-air temperature		–40	85	C

### Notes:

1. Absolute maximum of I<sub>O</sub> must be observed.
2. Unused control inputs must be held HIGH or LOW to prevent them from floating.
- 3 As measured between 0.8V and 2.0V, V<sub>DD</sub>=3.0V.

**Electrical Characteristics over Recommended Operating Free-Air Temperature Range**  
 (unless otherwise noted)

**DC Characteristics (2.7V < V<sub>DD</sub> ≤ 3.6V)**

	Parameter	Conditions	V <sub>DD</sub>	Min.	Typ.	Max.	Units
V <sub>IK</sub>	Input Clamp Diode	I <sub>IK</sub> = -18mA	3.0			-1.2	
V <sub>OH</sub>	HIGH Level Output Voltage	I <sub>OH</sub> = -100µA	2.7 - 3.6	V <sub>DD</sub> - 0.2			V
		I <sub>OH</sub> = -12mA	2.7	2.2			
		I <sub>OH</sub> = -18mA		2.4			
		I <sub>OH</sub> = -24mA	3.0	2.2			
		I <sub>OH</sub> = -32mA		2.0			
V <sub>OL</sub>	LOW Level Output Voltage	I <sub>OL</sub> = 100µA	2.7 - 3.6			0.2	V
		I <sub>OL</sub> = 12mA	2.7			0.4	
		I <sub>OL</sub> = 18mA				0.4	
		I <sub>OL</sub> = 24mA	3.0			0.45	
		I <sub>OL</sub> = 32mA				0.5	
		I <sub>OL</sub> = 64mA				0.75	
I <sub>I</sub>	Input Leakage Current	V <sub>I</sub> = V <sub>DD</sub> , or GND	3.6			±5.0	µA
I <sub>OZ</sub>	3-State Output Leakage	V <sub>O</sub> = 3.6V	2.7			±10	
I <sub>OFF</sub>	Power-OFF Leakage Current	V <sub>I</sub> or V <sub>O</sub> ≤ 3.6V	0			10	
I <sub>HOLD</sub>	Bus Hold Current A or B Outputs	V <sub>I</sub> = 0.8V	3.0	75			
		V <sub>I</sub> = 2.0V		-75			
		V <sub>I</sub> = 0 to 3.6V	3.6			±500	
I <sub>DD</sub>	Quiescent Supply Current	V <sub>I</sub> = V <sub>DD</sub> or GND	2.7 - 3.6			50	
		V <sub>DD</sub> ≤ (V <sub>I</sub> , V <sub>O</sub> ) ≤ 3.6V				±50	
ΔI <sub>DD</sub>	Increase in I <sub>DD</sub> per input	V <sub>IH</sub> = V <sub>DD</sub> - 0.6V, Other inputs at V <sub>DD</sub> or GND				400	

**Electrical Characteristics over Recommended Operating Free-Air Temperature Range**

(unless otherwise noted; continued from previous page)

**DC Characteristics (2.3V ≤ V<sub>DD</sub> ≤ 2.7V)**

Description	Parameters	Conditions	V <sub>DD</sub>	Min.	Typ.	Max.	Units
V <sub>IK</sub>	Input Clamp Diode	I <sub>IK</sub> = -18mA	2.3			-1.2	
V <sub>OH</sub>	HIGH Level Output Voltage	I <sub>OH</sub> = -100µA	2.3 - 2.7	V <sub>DD</sub> - 0.2			
		I <sub>OH</sub> = -12mA		1.8			
		I <sub>OH</sub> = -18mA		1.7			
V <sub>OL</sub>	LOW Level Output Voltage	I <sub>OL</sub> = 100µA	2.3 - 2.7			0.2	
		I <sub>OL</sub> = 12mA				0.4	
		I <sub>OL</sub> = 18mA				0.5	
		I <sub>OL</sub> = 24mA				0.55	
I <sub>I</sub>	Input Leakage Current	V <sub>I</sub> = V <sub>DD</sub> or GND	2.7			±5.0	
I <sub>OZ</sub>	3-State Output Leakage	V <sub>O</sub> = 3.6V	2.3			±10	
I <sub>OFF</sub>	Power-OFF Leakage Current	V <sub>I</sub> or V <sub>O</sub> ≤ 3.6V	0			10	
I <sub>HOLD</sub> <sup>(1)</sup>	Bus Hold Current A or B Outputs	V <sub>I</sub> = 0.7V	2.5		90		
		V <sub>I</sub> = 1.7V			-90		
I <sub>DD</sub>	Quiescent Supply Current	V <sub>I</sub> = V <sub>DD</sub> or GND	2.3 - 2.7			40	
		V <sub>DD</sub> ≤ (V <sub>I</sub> , V <sub>O</sub> ) ≤ 3.6V				±40	
ΔI <sub>DD</sub>	Increase in I <sub>DD</sub> per input	V <sub>IH</sub> = V <sub>DD</sub> - 0.6V, Inputs at V <sub>DD</sub> or Gnd				400	

**Note:**

1. Not Guaranteed

### Electrical Characteristics over Recommended Operating Free-Air Temperature Range

(unless otherwise noted; continued from previous page)

#### DC Characteristics ( $1.65V \leq V_{DD} \leq 1.95V$ )

Description	Parameters	Conditions	V <sub>DD</sub>	Min.	Typ.	Max.	Units
V <sub>IK</sub>	Input Clamp Diode	I <sub>IK</sub> = -18mA	1.65			-1.2	V
V <sub>OH</sub>	HIGH Level Output Voltage	I <sub>OH</sub> = -100µA	1.65-1.95	V <sub>DD</sub> -0.2			
		I <sub>OH</sub> = -6mA	1.65	1.4			
V <sub>OL</sub>	LOW Level Output Voltage	I <sub>OL</sub> = 100µA				0.2	
		I <sub>OL</sub> = 6mA				0.3	
I <sub>I</sub>	Input Leakage Current	V <sub>I</sub> = V <sub>DD</sub> or GND	1.95			±5.0	µA
I <sub>OZ</sub>	3-State Output Leakage	V <sub>O</sub> = 3.6V	1.65			±10	
I <sub>OFF</sub>	Power-OFF Leakage Current	V <sub>I</sub> = V <sub>O</sub> ≤ 3.6V	0			10	
I <sub>HOLD</sub> <sup>(1)</sup>	Bus Hold Current A or B Outputs	V <sub>I</sub> = 0.4	1.65		50		
		V <sub>I</sub> = 1.3			-50		
I <sub>DD</sub>	Quiescent Supply Current	V <sub>I</sub> = V <sub>DD</sub> or GND	1.65-1.95			20	
		V <sub>DD</sub> ≤ (V <sub>I</sub> , V <sub>O</sub> ) ≤ 3.6V				±20	
ΔI <sub>DD</sub>	Increase in I <sub>DD</sub> per input	V <sub>I</sub> = V <sub>DD</sub> -06V, Other inputs at V <sub>DD</sub> or Gnd				400	

**Note:**

1. Not Guaranteed

**Timing Requirements** (Over recommended operating free-air temperature range, unless otherwise noted, see Figures 1 thru 4)

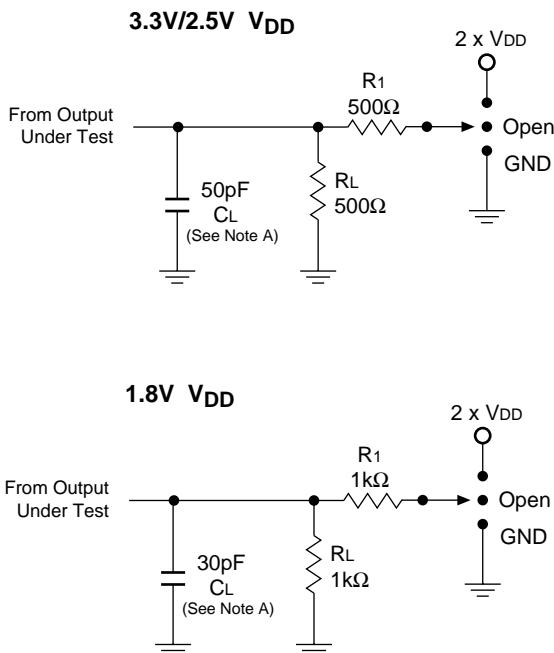
	$V_{CC} = 1.8V \pm 0.15V$		$V_{CC} = 2.5V \pm 0.2V$		$V_{CC} = 3.3V \pm 0.3V$		<b>Units</b>
	<b>Min</b>	<b>Max</b>	<b>Min</b>	<b>Max</b>	<b>Min</b>	<b>Max</b>	
$f_{clock}$ Clock Frequency		150		180		180	MHz
$t_w$ Pulse duration, CLK high or low			3.0		3.0		
$t_{su}$ Setup time, A before CLKAB↑, or B before CLKBA↑	2.5		2.0		1.6		ns
$t_h$ Hold time, A after CLKAB↑, or B after CLKBA↑	0.0		0.0		0.5		

**Switching Characteristics over recommended operating free-air temperature range**  
(unless otherwise noted, see Figures 1 thru 4)

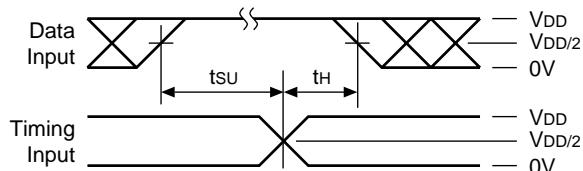
<b>Parameters</b>	<b>From (Input)</b>	<b>To (Output)</b>	$V_{CC} = 1.8V \pm 0.15V$		$V_{CC} = 2.5V \pm 0.2V$		$V_{CC} = 3.3V \pm 0.3V$		<b>Units</b>
			<b>Min.</b>	<b>Max.</b>	<b>Min.</b>	<b>Max.</b>	<b>Min.</b>	<b>Max.</b>	
$f_{max}$			150		180		180		MHz
$t_{pd}$	A or B	B or A	1.2	4.5	1.0	4.0	1.0	3.8	ns
	CLKAB or CLKBA	A or B	1.5	5.5	1.2	5.0	1.0	4.0	
	SAB or SBA	B or A	1.4	5.0	1.1	4.5	1.0	4.0	
$t_{en}$	$\overline{OE}$ or OE	A or B	1.4	5.0	1.6	5.0	1.6	4.0	
$t_{dis}$			1.5	5.5	2.0	5.0	2.0	4.0	

## Test Circuits and Switching Waveforms

### Parameter Measurement Information ( $V_{DD} = 1.65V - 3.6V$ )



## Setup, Hold, and Release Timing



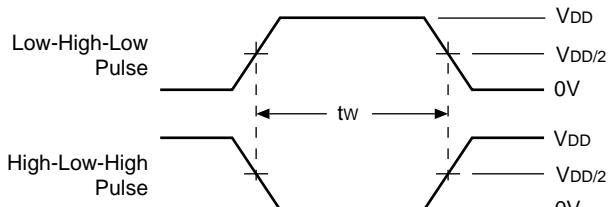
### Notes:

- $C_L$  includes probe and jig capacitance.
- Waveform 1 is for an output with internal conditions such that the output is LOW except when disabled by the output control.
- Waveform 2 is for an output with internal conditions such that the output is HIGH except when disabled by the output control.
- All input pulses are supplied by generators having the following characteristics:  $PRR \leq 10\text{ MHz}$ ,  $Z_O = 50\Omega$ ,  $t_r \leq 2\text{ ns}$ ,  $t_f \leq 2\text{ ns}$ , **measured from 10% to 90%, unless otherwise specified.**
- The outputs are measured one at a time with one transition per measurement.

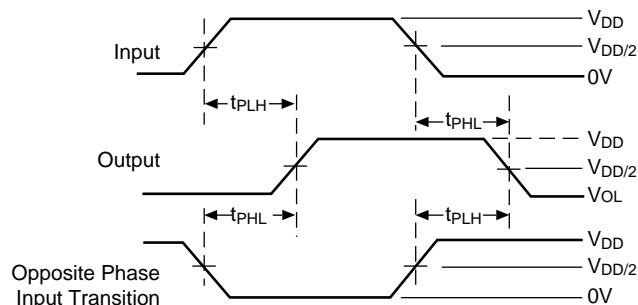
## Switch Position

Test	S1
$t_{PD}$	Open
$t_{PLZ}/t_{PZL}$	$2 \times V_{DD}$
$t_{PHZ}/t_{PZH}$	GND

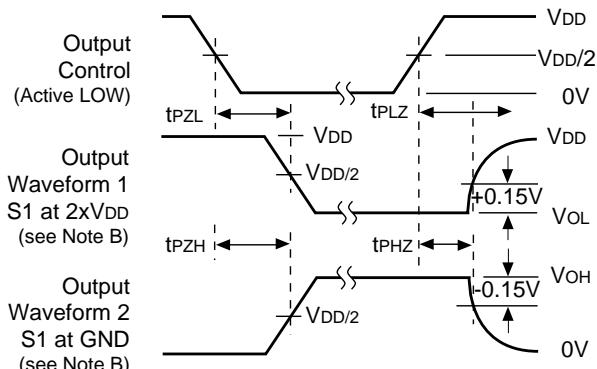
## Pulse Width



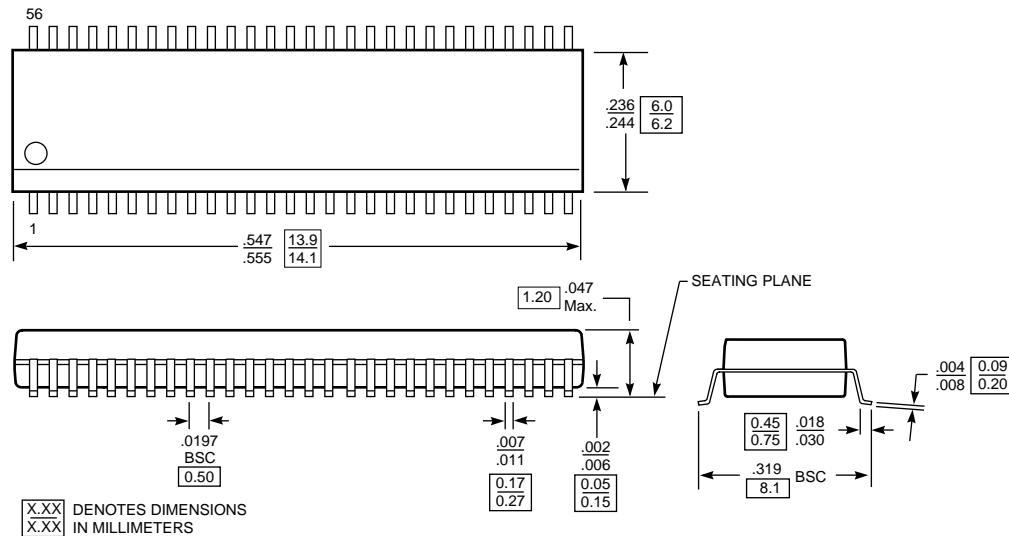
## Propagation Delay



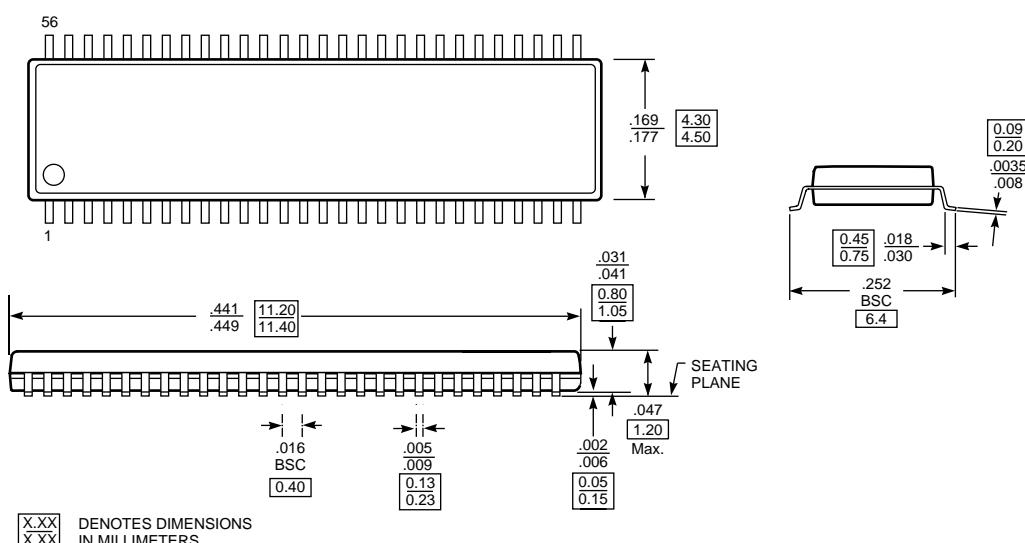
## Enable Disable Timing



### Packaging Mechanical: 56-pin TSSOP (A)



### Packaging Mechanical: 56-pin TVSOP (K)



Ordering Information	Package - Pins
PI74ALVTC16652A	TSSOP - 56
PI74ALVTC16652K	TVSOP - 56